# Fabrication of Through Silicon Via (TSV) and Application


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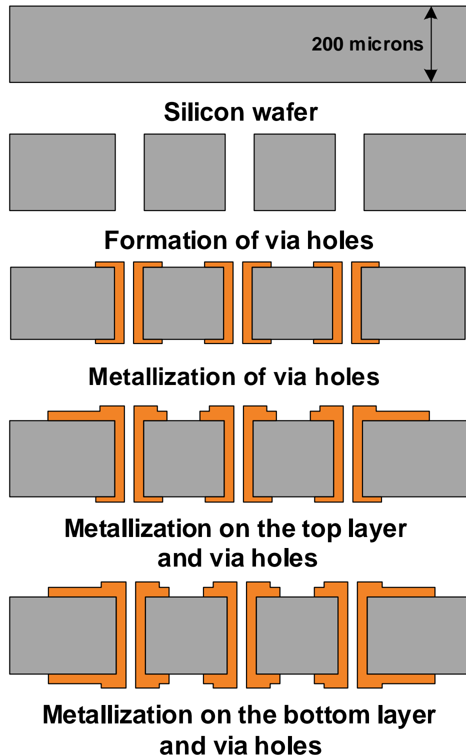
NNIN Facility utilized: Nanofabrication Center and Characterization Facility

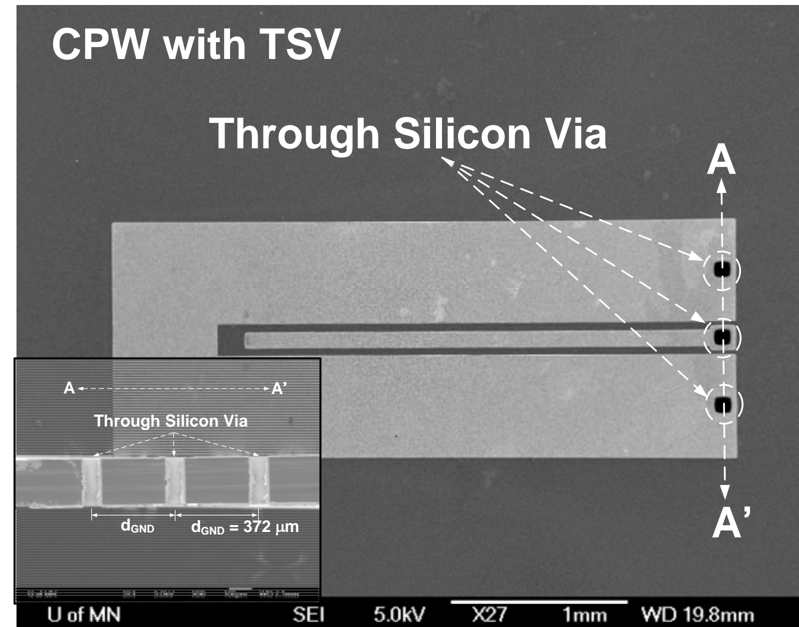

## Objectives of work

- Development of TSV fabrication process
- Characterization of TSV interconnect




## Major observations

- Fabrication process for TSV has been developed.
- The TSV has been used to develop ultra-broadband (DC-110 GHz) 3D CPW interconnect.




## Publications


- Y. S. Cho and R. Franklin, "Novel Broadband Through Silicon Via Interconnect for Three Dimensional CPW Transition," *Microwave Conference (EuMC), 2010 European* , vol., no., pp.113-116, 28-30 Sept. 2010.